

RJK03P7DPA

MOS1 30 V, 15 A, 9.4 mΩ max.

MOS2 30 V, 30 A, 5.3 mΩ max.

Built in SBD Dual N-channel Power MOS FET

High Speed Power Switching

R07DS0906EJ0110

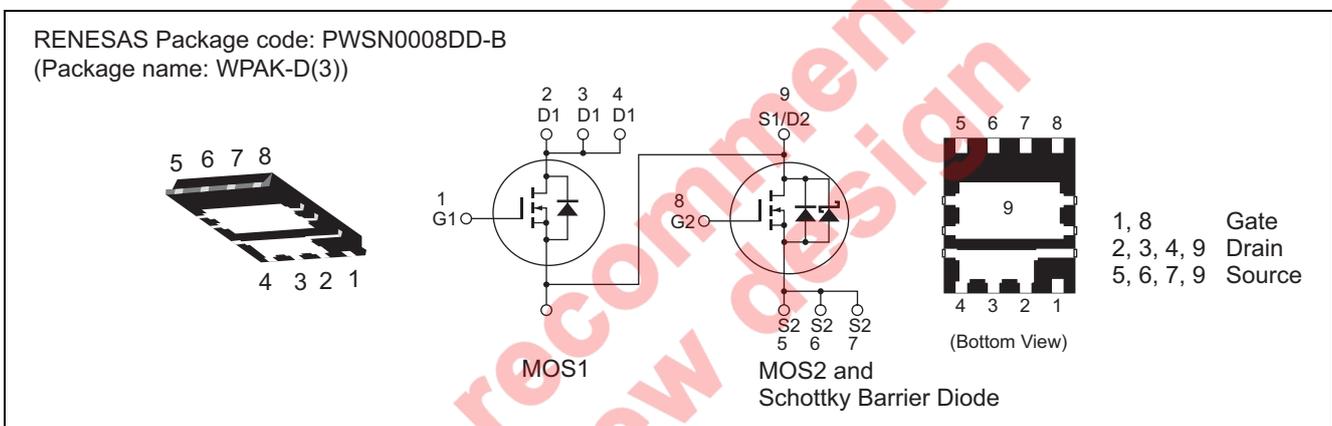
Rev.1.10

Nov 01, 2012

Features

- Low on-resistance
- Capable of 4.5 V gate drive
- High density mounting
- Pb-free
- Halogen-free

Outline



Absolute Maximum Ratings

(Ta = 25°C)

Item	Symbol	Ratings		Unit
		MOS1	MOS2	
Drain to source voltage	V_{DSS}	30	30	V
Gate to source voltage	V_{GSS}	±20	±20	V
Drain current	I_D	15	30	A
Drain peak current	$I_{D(pulse)}$ ^{Note1}	60	120	A
Reverse drain current	I_{DR}	15	30	A
Avalanche current	I_{AP} ^{Note 2}	8.5	12	A
Avalanche energy	E_{AS} ^{Note 2}	7.23	14.4	mJ
Channel dissipation	P_{ch} ^{Note3}	10	20	W
Channel temperature	Tch	150	150	°C
Storage temperature	Tstg	-55 to +150	-55 to +150	°C

- Notes: 1. $PW \leq 10 \mu s$, duty cycle $\leq 1\%$
 2. Value at Tch = 25°C, Rg $\geq 50 \Omega$
 3. Tc=25°C

Electrical Characteristics

• MOS1

(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	30	—	—	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source leak current	I_{GSS}	—	—	± 0.5	μA	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	1	μA	$V_{DS} = 24 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.2	—	2.5	V	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$
Static drain to source on state resistance	$R_{DS(on)}$	—	7.8	9.4	$\text{m}\Omega$	$I_D = 7.5 \text{ A}, V_{GS} = 10 \text{ V}$ ^{Note4}
	$R_{DS(on)}$	—	9.7	12.6	$\text{m}\Omega$	$I_D = 7.5 \text{ A}, V_{GS} = 4.5 \text{ V}$ ^{Note4}
Forward transfer admittance	$ y_{fs} $	—	36	—	S	$I_D = 7.5 \text{ A}, V_{DS} = 5 \text{ V}$ ^{Note4}
Input capacitance	C_{iss}	—	850	1190	pF	$V_{DS} = 10 \text{ V}$
Output capacitance	C_{oss}	—	150	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	C_{rss}	—	80	—	pF	$f = 1 \text{ MHz}$
Gate Resistance	R_g	—	1.55	3.1	Ω	
Total gate charge	Q_g	—	7.1	—	nC	$V_{DD} = 10 \text{ V}$
Gate to source charge	Q_{gs}	—	2.3	—	nC	$V_{GS} = 4.5 \text{ V}$
Gate to drain charge	Q_{gd}	—	2.0	—	nC	$I_D = 15 \text{ A}$
Turn-on delay time	$t_{d(on)}$	—	2.8	—	ns	$V_{GS} = 10 \text{ V}, I_D = 7.5 \text{ A}$
Rise time	t_r	—	1.7	—	ns	$V_{DD} \approx 10 \text{ V}$
Turn-off delay time	$t_{d(off)}$	—	12.6	—	ns	$R_L = 1.3 \Omega$
Fall time	t_f	—	3.5	—	ns	$R_g = 4.7 \Omega$
Body–drain diode forward voltage	V_{DF}	—	0.84	1.09	V	$I_F = 15 \text{ A}, V_{GS} = 0$ ^{Note4}
Body–drain diode reverse recovery time	t_{rr}	—	8.1	—	ns	$I_F = 15 \text{ A}, V_{GS} = 0$ $di_F/dt = 500 \text{ A}/\mu\text{s}$

Notes: 4. Pulse test

• MOS2

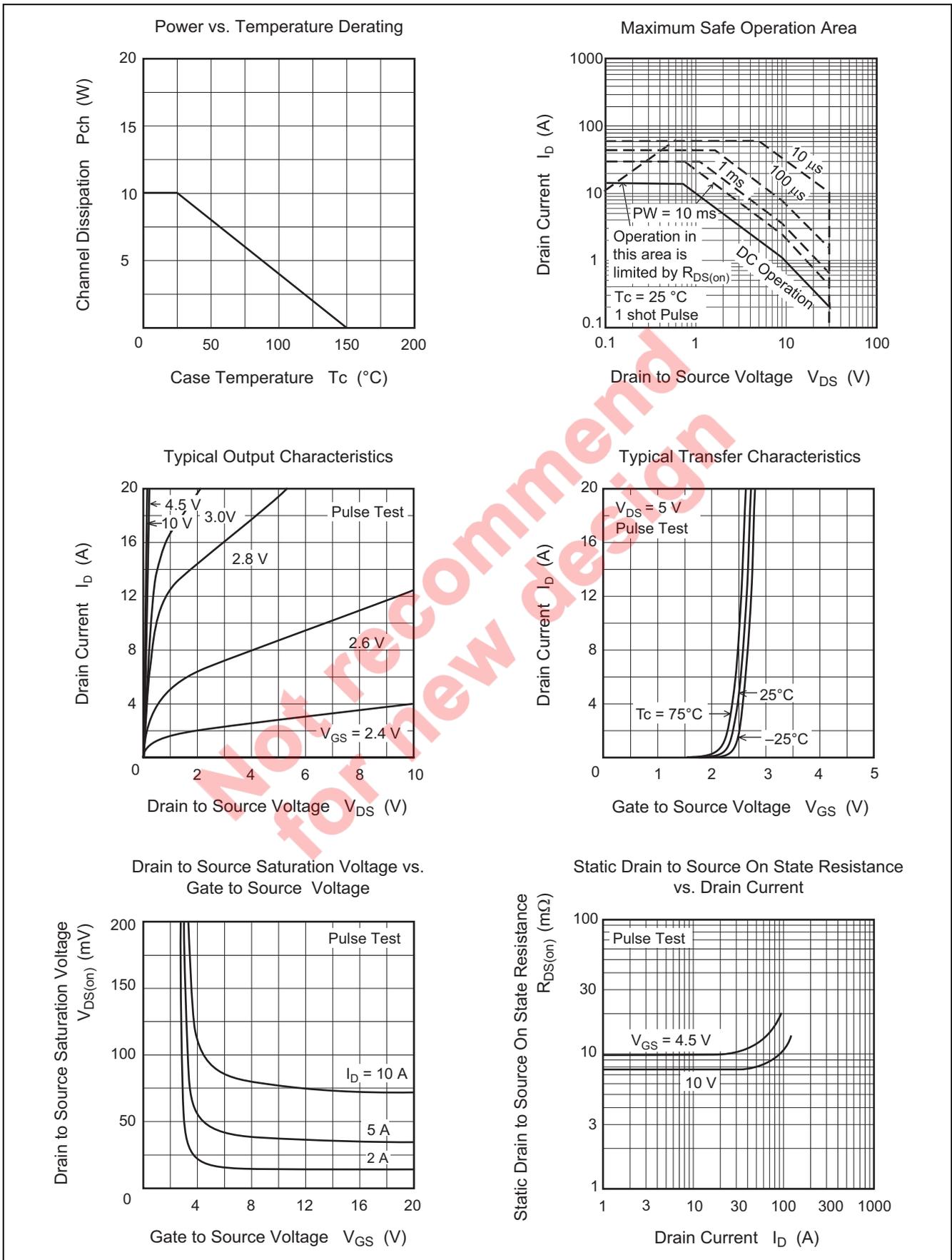
(Ta = 25°C)

Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	30	—	—	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source leak current	I_{GSS}	—	—	± 0.5	μA	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	I_{DSS}	—	—	1	mA	$V_{DS} = 24 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage	$V_{GS(off)}$	1.2	—	2.5	V	$V_{DS} = 10 \text{ V}, I_D = 1 \text{ mA}$
Static drain to source on state resistance	$R_{DS(on)}$	—	4.4	5.3	m Ω	$I_D = 15 \text{ A}, V_{GS} = 10 \text{ V}$ ^{Note4}
	$R_{DS(on)}$	—	5.4	7.0	m Ω	$I_D = 15 \text{ A}, V_{GS} = 4.5 \text{ V}$ ^{Note4}
Forward transfer admittance	$ y_{fs} $	—	65	—	S	$I_D = 15 \text{ A}, V_{DS} = 5 \text{ V}$ ^{Note4}
Input capacitance	C_{iss}	—	2110	2950	pF	$V_{DS} = 10 \text{ V}$
Output capacitance	C_{oss}	—	345	—	pF	$V_{GS} = 0$
Reverse transfer capacitance	C_{rss}	—	210	—	pF	$f = 1 \text{ MHz}$
Gate Resistance	R_g	—	1.5	3.0	Ω	
Total gate charge	Q_g	—	16.5	—	nC	$V_{DD} = 10 \text{ V}$
Gate to source charge	Q_{gs}	—	5.3	—	nC	$V_{GS} = 4.5 \text{ V}$
Gate to drain charge	Q_{gd}	—	5.5	—	nC	$I_D = 30 \text{ A}$
Turn-on delay time	$t_{d(on)}$	—	4.7	—	ns	$V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$
Rise time	t_r	—	2.9	—	ns	$V_{DD} \approx 10 \text{ V}$
Turn-off delay time	$t_{d(off)}$	—	35.2	—	ns	$R_L = 0.7 \Omega$
Fall time	t_f	—	11.4	—	ns	$R_g = 4.7 \Omega$
Schottky Barrier diode forward voltage	V_F	—	0.46	—	V	$I_F = 2 \text{ A}, V_{GS} = 0$ ^{Note4}
Body-drain diode reverse recovery time	t_{rr}	—	6.6	—	ns	$I_F = 30 \text{ A}, V_{GS} = 0$ $di_F/dt = 500 \text{ A}/\mu\text{s}$

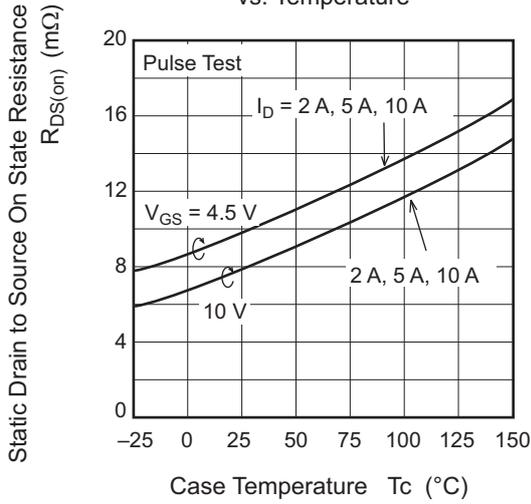
Notes: 4. Pulse

Main Characteristics

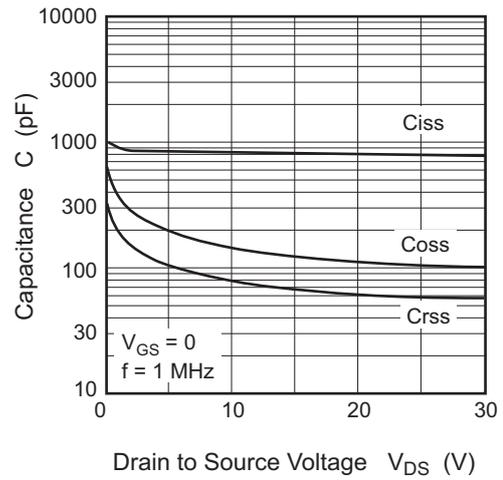
• MOS1



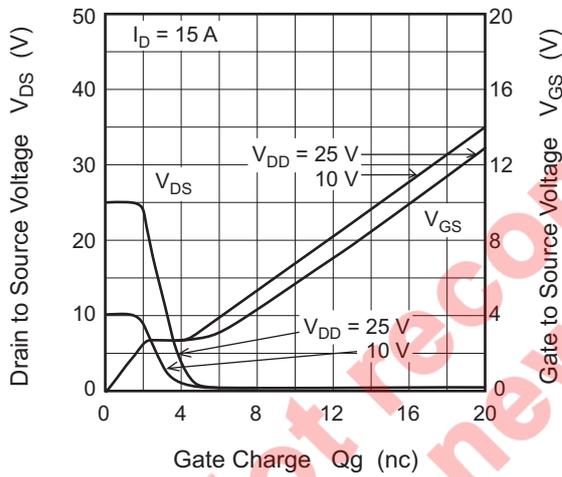
Static Drain to Source On State Resistance vs. Temperature



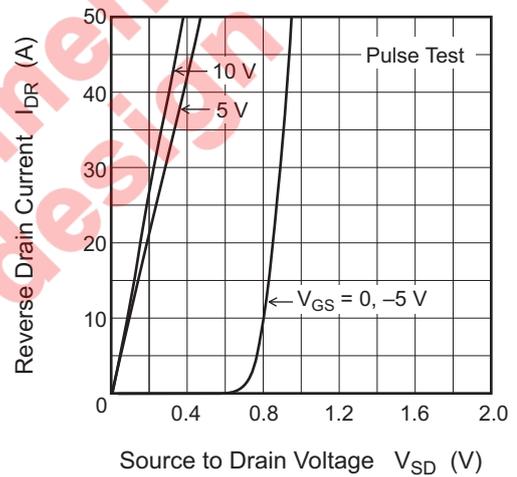
Typical Capacitance vs. Drain to Source Voltage



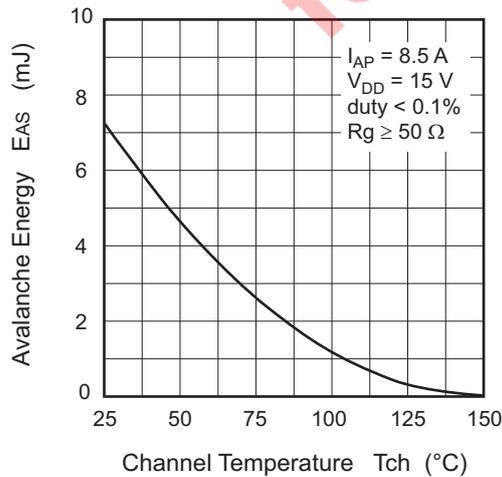
Dynamic Input Characteristics



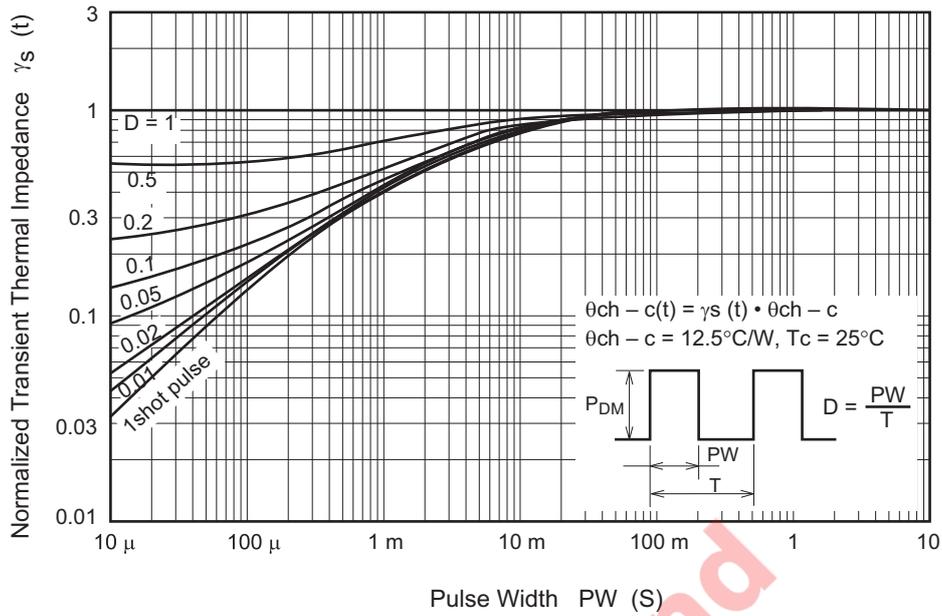
Reverse Drain Current vs. Source to Drain Voltage



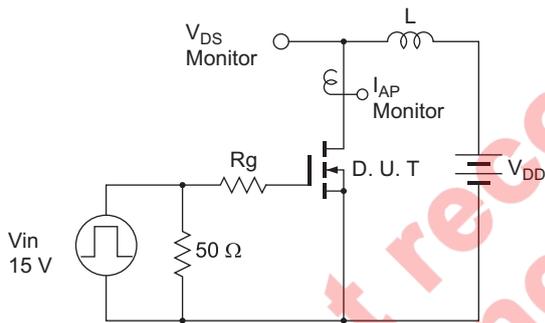
Maximum Avalanche Energy vs. Channel Temperature Derating



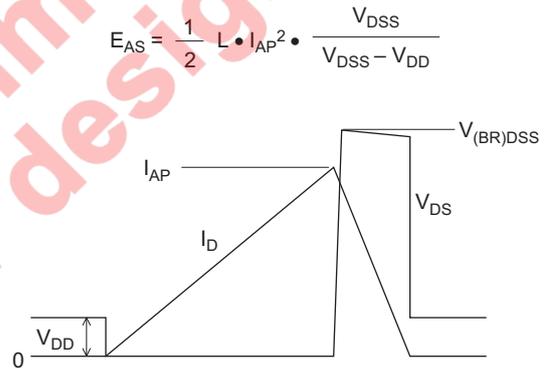
Normalized Transient Thermal Impedance vs. Pulse Width



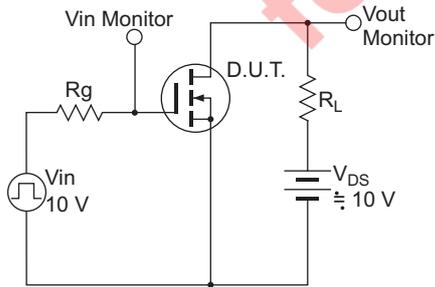
Avalanche Test Circuit



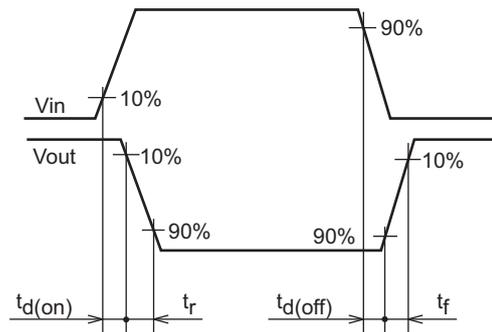
Avalanche Waveform



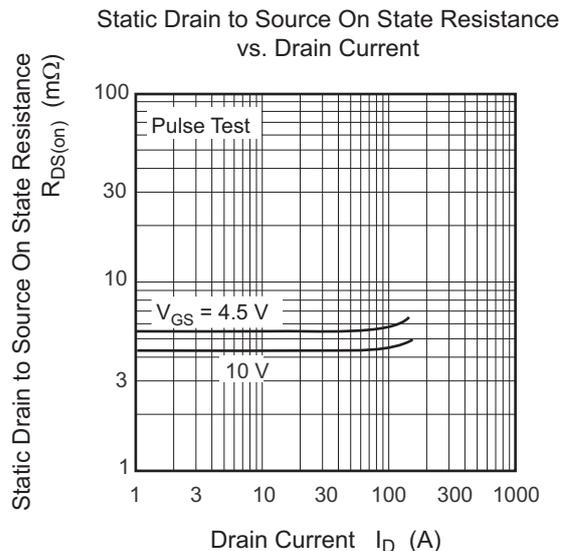
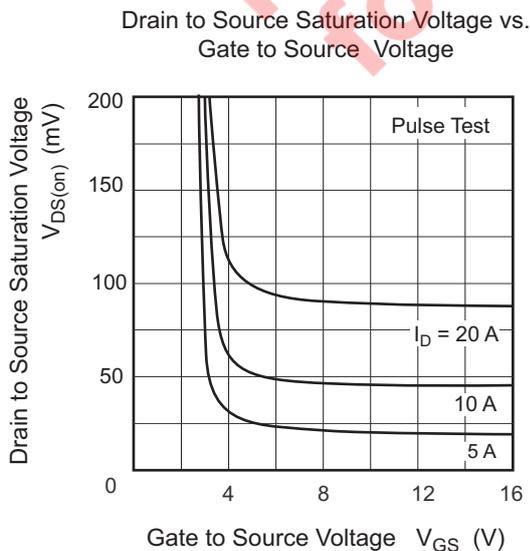
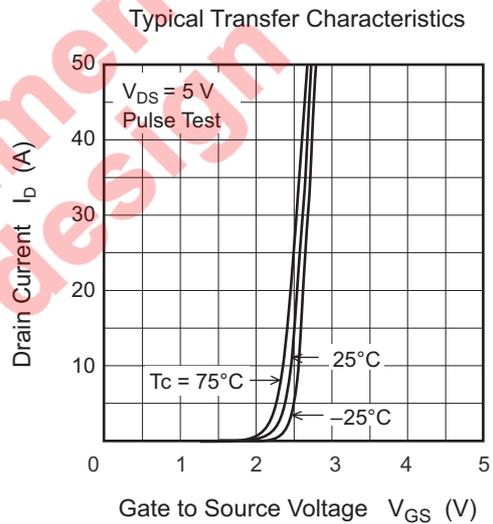
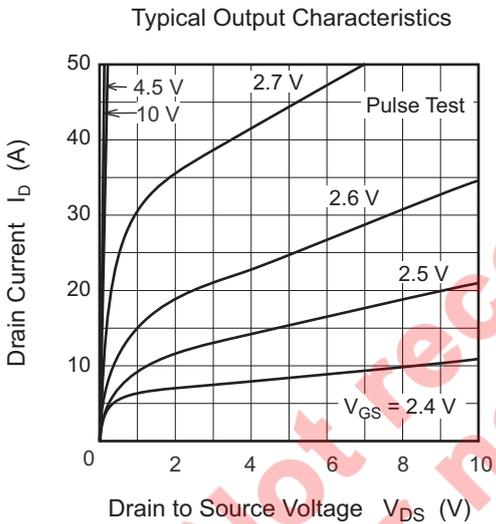
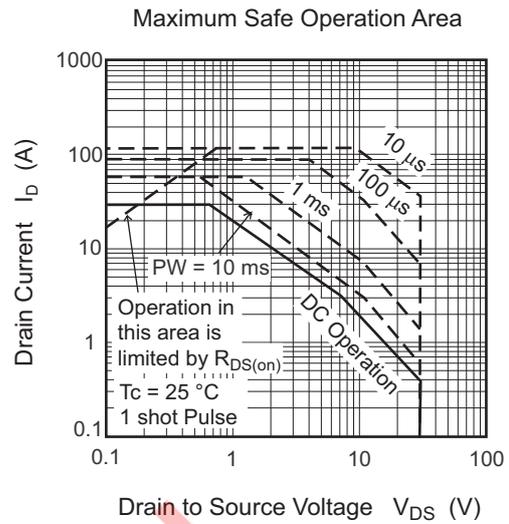
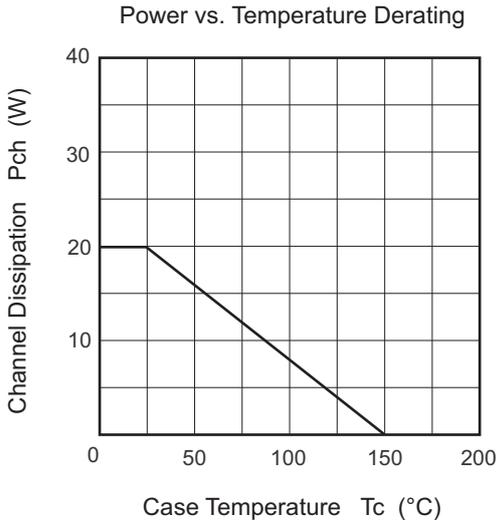
Switching Time Test Circuit

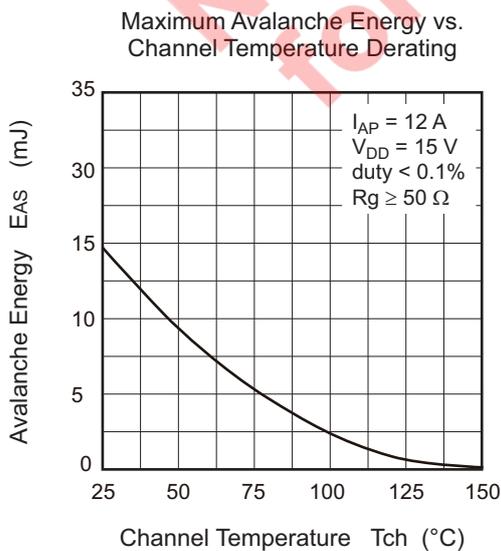
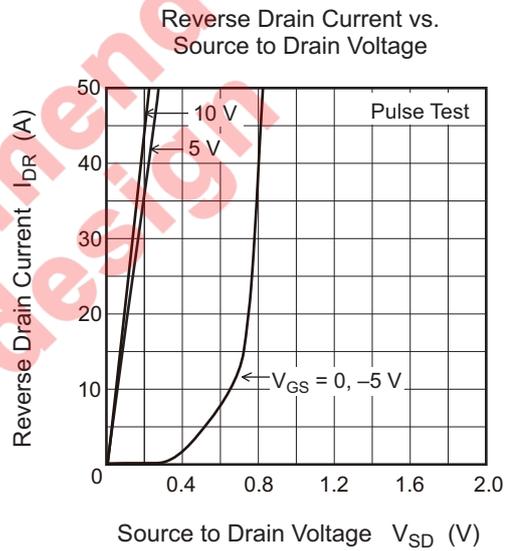
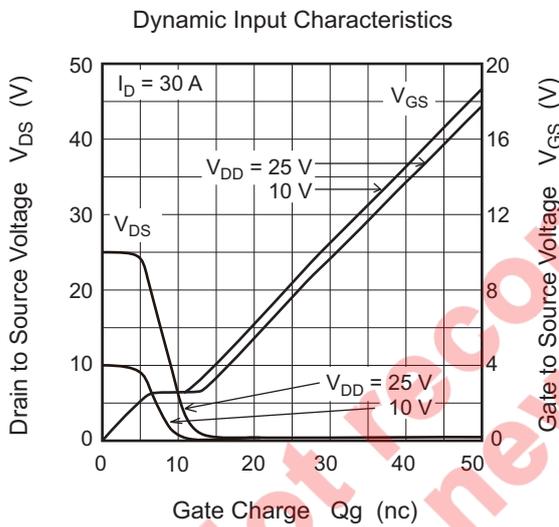
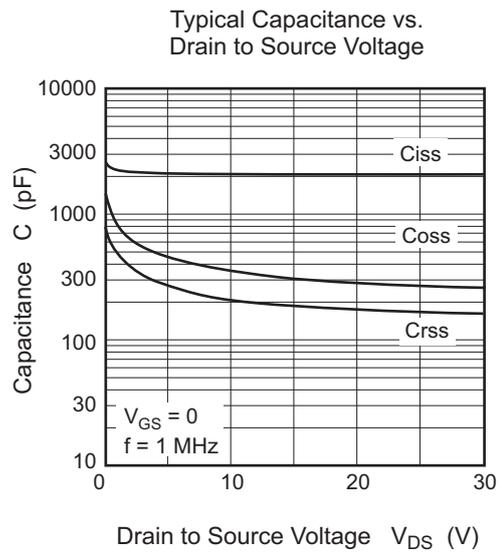
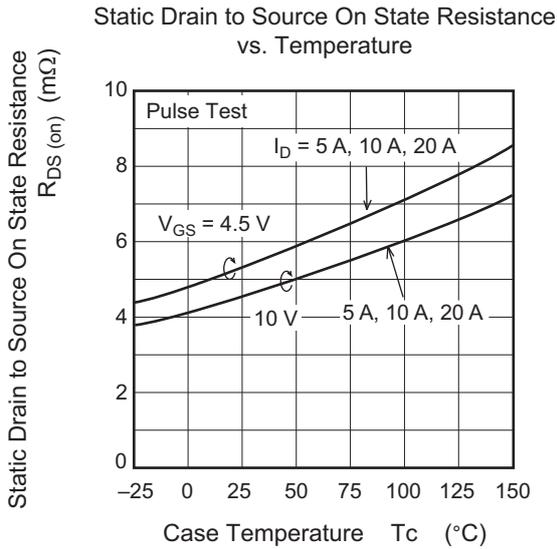


Switching Time Waveform

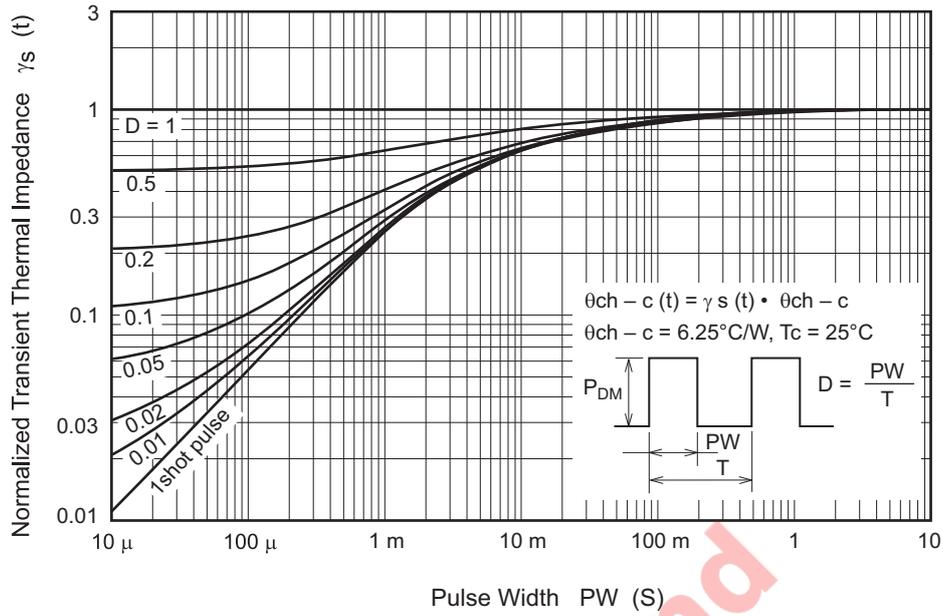


• MOS2 and Schottky Barrier Diode

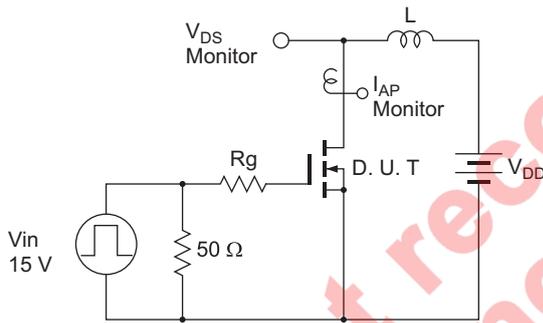




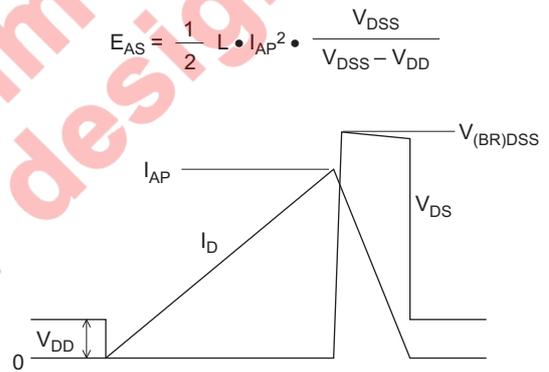
Normalized Transient Thermal Impedance vs. Pulse Width



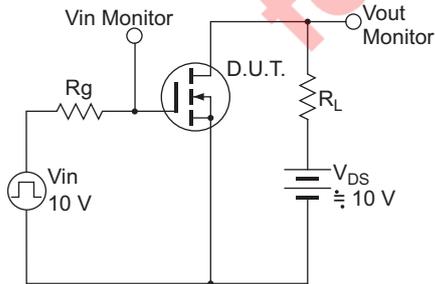
Avalanche Test Circuit



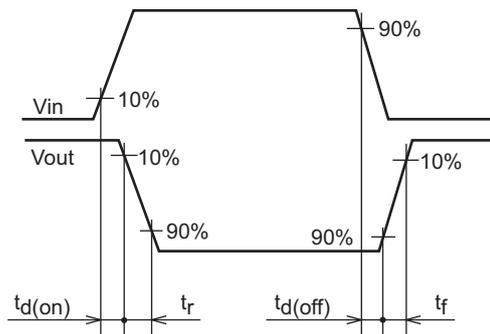
Avalanche Waveform



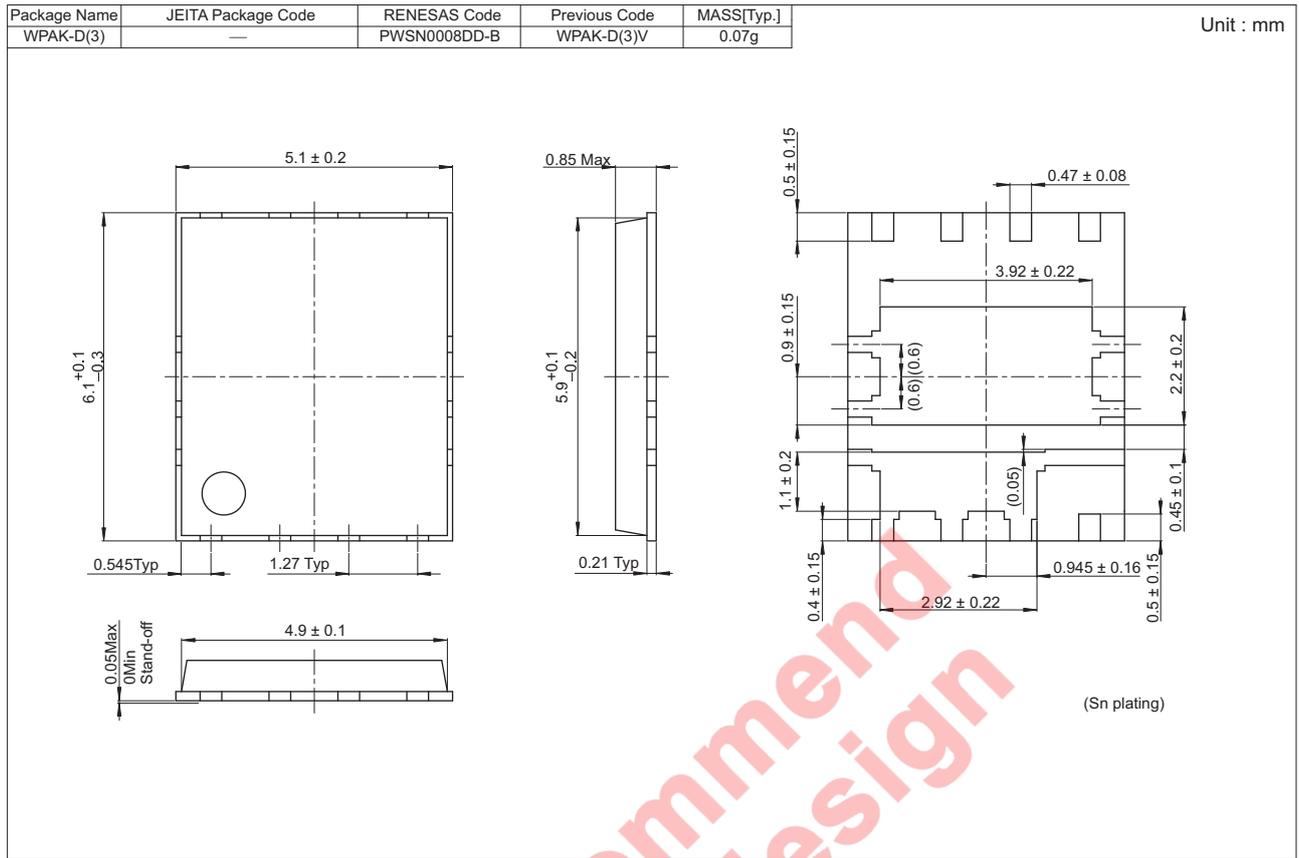
Switching Time Test Circuit



Switching Time Waveform



Package Dimensions



Ordering Information

Orderable Part Number	Quantity	Shipping Container
RJK03P7DPA-00-J5A	3000 pcs	Taping

Note: The symbol of 2nd "-" is occasionally presented as "#".

Not recommended for new design

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